

(O)DMB and FED upgrade for HL-LHC



Manuel Franco Sevilla (*UCSB*)

Evaldas Juska (*Texas A&M*)

7th of December 2016

Forward muon upgrade workshop

Texas A&M, College Station



	Current ODMBv1 2013	Virtex-6 XC6VLX130T- 1FFG1156C	Estimated ODMBv2 2020	Kintex-7 XC7K325T- 3FFG900E	Artix-7 XC7A200T- 3FFG1156E
Logic (slices)	8.1k	20k	15k	51k	33k
Total RAM	3 Mb	9.5 Mb	6 Mb	16 Mb	13 Mb
Clock managers	2	10	4	10	10
I/O	300	600	379	500	500
Opt. transceivers	8 @ 3.2 Gbps	20 @ 5 Gbps	12	16 @ 12.5 Gbps	16 @ 6.6 Gbps
Price		\$700-1,000		\$1,940	\$325

- ~ The Artix-7 is much cheaper *today* than the Kintex 7
 - Only drawback seems to be links at half-speed
 - Covers needs with more fiber links
- ~ Might save money even with prices coming down and additional CTP7 boards

~ **Option A:** run all ODMB links at 10Gbs+

- ME1/1 = 3 links
- ME2/1 = 2 links
- ME3/1, ME4/1 = 1 link
- CTP7s needed = 12
- Using VTTx in ME2/1 due to FP space constraints
- Could fit to 11, but doesn't make sense - not a multiple of 2 (endcaps)
- ODMB has to use Kintex7 on all boards = expensive

~ **Option B:** ME1/1 at 10Gbs+, others at 6.4Gbs

- ME1/1 = 3 links
- ME2/1 = 2 links (**safety factor = 1.88**)
- ME3/1 and ME4/1 = 2 links
- **Depending on final rate numbers, might require 3 links in ME2/1 → will need more expensive 4-link TX**
- CTP7s needed = 12
- Only 1 spare RX left -- that's probably ok even if using multifiber "SLink" (?)
- CTP7 cost unchanged
- ODMB uses Kintex7 on ME1/1, Artix7 on ME2/1, ME3/1, ME4/1
- Saves 180 k\$

~ **Option 3:** all ODMBs run at 6.4Gbs

- ME1/1 = 4 links
- ME2/1 = 2 links (**safety factor = 1.88**)
- ME3/1, ME4/1 = 2 links
- **Depending on final rate numbers, might require 3 links in ME2/1 → will need more expensive 4-link TX**
- CTP7s needed = 14
- Awkward mapping but enough links, would work
- ODMB uses Artix7 in all cases
- 115k savings on ME1/1 alone - compared to option 2 (excluding spares)
- CTP7 cost goes up by 30k

- ~ **Note:** with a small design change on CTP7 RX count could be increased to 72 (CTP7 has 13 backplane links -- not used in CSC)
- Seems not worth it
 - Option 3 could fit to 12 boards but no RX is left for DAQ backpressure
 - Option 1 could fit to 10 boards but no RX is left for DAQ backpressure
 - May be possible to increase CTP7 RX count to ~79 in the expense of removing 12 TXs -- might be worth it (total TX count = 36)
 - Redesign costs unclear -- have to check with University of Wisconsin
 - Replace one TX MiniPOD with RX MiniPOD, possibly small routing change

~ Current costs of ODMB FPGAs and CTP7

→ 2 k\$ for Kintex7, 0.325 k\$ for Artix7

→ 15 k\$ for each CTP7

Option	# Kintex7	# Artix7	# CTP7	# links	k\$ FPGA	k\$ CTP7	k\$ sum
A	180	0	12	356	360	180	540 k\$
B	72	108	12	432	179	180	359 k\$
C	0	180	14	504	59	210	269 k\$

~ Not included cost of additional fibers and μ TCA crate

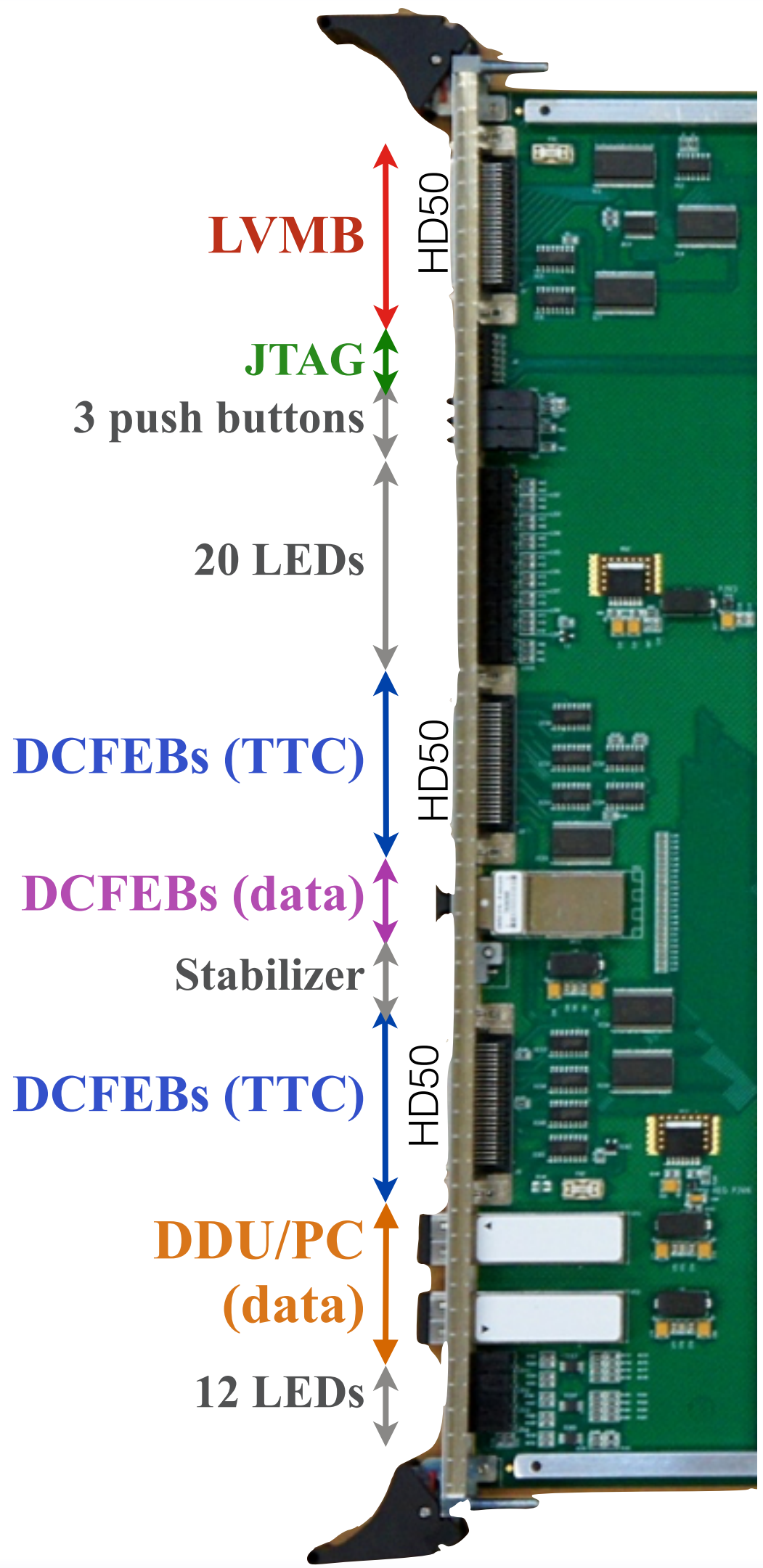
~ Not included savings from spares (~10%)

Concerns about rate or other limitations?

Backup

Main features of PCB design quite similar in both cases

ODMBv2.1



ME1/1

- One front panel change with respect to **ODMB 2013**
- * **Replace 4.25 Gbps transceivers with 10+ Gbps parts**

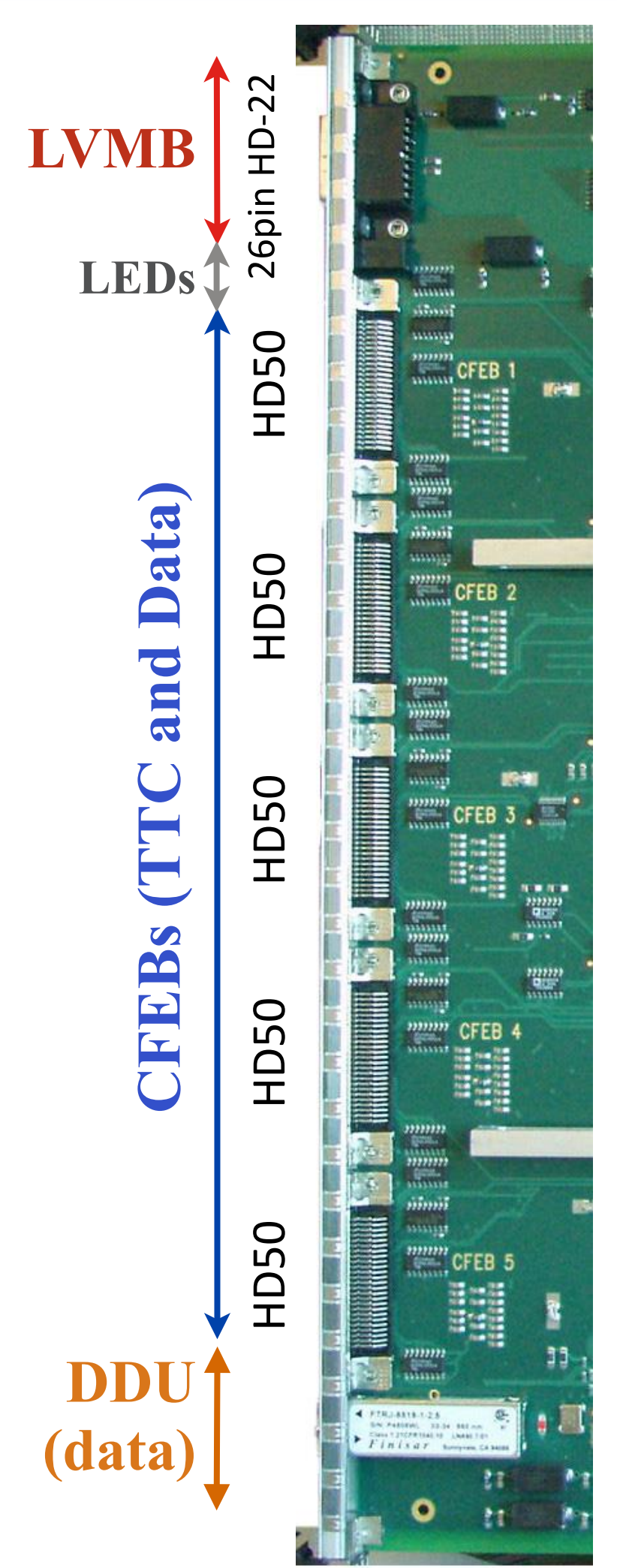
ME234/1

- Two front panel changes with respect to **DMB 2003**
- * **Replace 4.25 Gbps transceivers with 10+ Gbps parts**
- * **Remove LEDs, install snap-12**
- * **Place JTAG connector on board**

- ~ Current FTLF8524E2GNL: **4.25 Gbps, \$40**
- ~ Similar Finisar transceiver FTLX8571D3BCV
 - ➔ **10.3 Gbps, \$73, two needed for ME1/1**
- ~ Multilane transceiver would give more flexibility
 - ➔ AFBR-79EEPZ: **four 10.3 Gbps links, \$368**
 - ➔ AFBR-79FIPZ: **four 16 Gbps links**



ODMBv2.2



Design in 4-5 years → prices will come down/new tech

Kintex-7 product table

Kintex-7

	Part Number	XC7K70T	XC7K160T	XC7K325T	XC7K355T	XC7K410T	XC7K420T	XC7K480T
	EasyPath™ Cost Reduction Solutions ⁽¹⁾	—	—	XCE7K325T	XCE7K355T	XCE7K410T	XCE7K420T	XCE7K480T
Logic Resources	Slices	10,250	25,350	50,950	55,650	63,550	65,150	74,650
	Logic Cells	65,600	162,240	326,080	356,160	406,720	416,960	477,760
	CLB Flip-Flops	82,000	202,800	407,600	445,200	508,400	521,200	597,200
Memory Resources	Maximum Distributed RAM (Kb)	838	2,188	4,000	5,088	5,663	5,938	6,788
	Block RAM/FIFO w/ ECC (36 Kb each)	135	325	445	715	795	835	955
	Total Block RAM (Kb)	4,860	11,700	16,020	25,740	28,620	30,060	34,380
Clock Resources	CMTs (1 MMCM + 1 PLL)	6	8	10	6	10	8	8
I/O Resources	Maximum Single-Ended I/O	300	400	500	300	500	400	400
	Maximum Differential I/O Pairs	144	192	240	144	240	192	192
Integrated IP Resources	DSP48 Slices	240	600	840	1,440	1,540	1,680	1,920
	PCIe® Gen2 ⁽²⁾	1	1	1	1	1	1	1
	Analog Mixed Signal (AMS) / XADC	1	1	1	1	1	1	1
	Configuration AES / HMAC Blocks	1	1	1	1	1	1	1
	GTX Transceivers (12.5 Gb/s Max Rate)	8	8	16	24	16	32	32
Speed Grades	Commercial	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2
	Extended	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3
	Industrial	-1, -2	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L
	Package ⁽³⁾	Dimensions (mm)		Available User I/O: 3.3V HR I/O, 1.8V HP I/Os (GTX)				
Footprint Compatible	FBG484 / FBV484	23 x 23	185, 100 (4)	185, 100 (4)				
	FBG676 / FBV676	27 x 27	200, 100 (8)	250, 150 (8)	250, 150 (8)		250, 150 (8)	
	FFG676 / FFV676	27 x 27		250, 150 (8)	250, 150 (8)		250, 150 (8)	
Footprint Compatible	FBG900 / FBV900	31 x 31		350, 150 (16)			350, 150 (16)	
	FFG900 / FFV900	31 x 31		350, 150 (16)			350, 150 (16)	
	FFG901 / FFV901	31 x 31			300, 0 (24)		380, 0 (28)	380, 0 (28)
	FFG1156 / FFV1156	35 x 35					400, 0 (32)	400, 0 (32)

FBG / FBV: 1.0 mm Lidless flip-chip; FFG / FFV: 1.0 mm Flip-chip fine-pitch

XMP085 (v3.8)

Artix-7 product table



		Artix®-7 FPGAs Optimized for Lowest Cost and Lowest Power Applications (1.0V, 0.95V, 0.9V)						
	Part Number	XC7A15T	XC7A35T	XC7A50T	XC7A75T	XC7A100T	XC7A200T	
Logic Resources	Logic Cells	16,640	33,280	52,160	75,520	101,440	215,360	
	Slices	2,600	5,200	8,150	11,800	15,850	33,650	
	CLB Flip-Flops	20,800	41,600	65,200	94,400	126,800	269,200	
Memory Resources	Maximum Distributed RAM (Kb)	200	400	600	892	1,188	2,888	
	Block RAM/FIFO w/ ECC (36 Kb each)	25	50	75	105	135	365	
	Total Block RAM (Kb)	900	1,800	2,700	3,780	4,860	13,140	
Clock Resources	CMTs (1 MMCM + 1 PLL)	5	5	5	6	6	10	
I/O Resources	Maximum Single-Ended I/O	250	250	250	300	300	500	
	Maximum Differential I/O Pairs	120	120	120	144	144	240	
Embedded Hard IP Resources	DSP Slices	45	90	120	180	240	740	
	PCIe® Gen2 ⁽¹⁾	1	1	1	1	1	1	
	Analog Mixed Signal (AMS) / XADC	1	1	1	1	1	1	
	Configuration AES / HMAC Blocks	1	1	1	1	1	1	
	GTP Transceivers (6.6 Gb/s Max Rate) ⁽²⁾	4	4	4	8	8	16	
Speed Grades	Commercial	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	
	Extended	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3	
	Industrial	-1, -2, -1L	-1, -2, -1L	-1, -2, -1L	-1, -2, -1L	-1, -2, -1L	-1, -2, -1L	
	Package ^{(3), (4)}	Dimensions (mm)						Available User I/O: 3.3V SelectIO™ HR I/O (GTP Transceivers)
	CPG236	10 x 10	106 (2)	106 (2)	106 (2)			
	CSG324	15 x 15	210 (0)	210 (0)	210 (0)	210 (0)	210 (0)	
	CSG325	15 x 15	150 (4)	150 (4)	150 (4)			
	FTG256	17 x 17	170 (0)	170 (0)	170 (0)	170 (0)	170 (0)	
	SBG484 / SBV484	19 x 19					285 (4)	
Footprint Compatible	FGG484	23 x 23	250 (4)	250 (4)	250 (4)	285 (4)	285 (4)	
	FBG484 / FBV484	23 x 23					285 (4)	
Footprint Compatible	FGG676	27 x 27				300 (8)	300 (8)	
	FBG676 / FBV676	27 x 27					400 (8)	
	FFG1156 / FFV1156	35 x 35					500 (16)	

Artix7 to be used,
16 MGT

XMP086 (v4.7)

CPG: 0.5 mm Wire-bond chip-scale; CSG: 0.8 mm Wire-bond chip-scale; FTG: 1.0 mm Wire-bond fine-pitch; SBG / SBV: 0.8 mm Lidless flip-chip; FGG: 1.0 mm Wire-bond fine-pitch; FBG / FBV 1.0 mm Lidless flip-chip; FFG / FFV: 1.0 mm Flip-chip fine-pitch

Virtex-6 product table

Current ODMB

	Part Number	XC6VLX75T	XC6VLX130T	XC6VLX195T	XC6VLX240T	XC6VLX365T	XC6VLX550T	XC6VLX760	XC6VSX315T	XC6VSX475T	XC6VHX250T	XC6VHX255T	XC6VHX380T	XC6VHX565T	
	EasyPath™ FPGA Cost Reduction Solutions ⁽¹⁾	XCE6VLX75T	XCE6VLX130T	XCE6VLX195T	XCE6VLX240T	XCE6VLX365T	XCE6VLX550T	XCE6VLX760	XCE6VSX315T	XCE6VSX475T	XCE6VHX250T	XCE6VHX255T	XCE6VHX380T	XCE6VHX565T	
Logic Resources	Slices ⁽²⁾	11,640	20,000	31,200	37,680	56,880	85,920	118,560	49,200	74,400	39,360	39,600	59,760	88,560	
	Logic Cells ⁽³⁾	74,496	128,000	199,680	241,152	364,032	549,888	758,784	314,880	476,160	251,904	253,440	382,464	566,784	
	CLB Flip-Flops	93,120	160,000	249,600	301,440	455,040	687,360	948,480	393,600	595,200	314,880	316,800	478,080	708,480	
Memory Resources	Maximum Distributed RAM (Kb)	1,045	1,740	3,040	3,650	4,130	6,200	8,280	5,090	7,640	3,040	3,050	4,570	6,370	
	Block RAM/FIFO w/ECC (36 Kb each)	156	264	344	416	416	632	720	704	1,064	504	516	768	912	
	Total Block RAM (Kb)	5,616	9,504	12,384	14,976	14,976	22,752	25,920	25,344	38,304	18,144	18,567	27,648	32,832	
Clock Resources	Mixed-Mode Clock Managers (MMCM)	6	10	10	12	12	18	18	12	18	12	12	18	18	
I/O Resources ^(4,5)	Maximum Single-Ended I/O	360	600	600	720	720	1,200	1,200	720	840	320	480	720	720	
	Maximum Differential I/O Pairs	180	300	300	360	360	600	600	360	420	160	240	360	360	
Embedded Hard IP Resources ⁽⁶⁾	DSP48E1 Slices	288	480	640	768	576	864	864	1,344	2,016	576	576	864	864	
	PCI Express® Interface Blocks	1	2	2	2	2	2	—	2	2	4	2	4	4	
	10/100/1000 Ethernet MAC Blocks	4	4	4	4	4	4	—	4	4	4	2	4	4	
	GTX Low-Power Transceivers	12	20	20	24	24	36	—	24	36	48	24	48	48	
	GTH High-Speed Transceivers	—	—	—	—	—	—	—	—	—	—	24	24	24	
Speed Grades	Commercial	-L1, -1, -2, -3	-L1, -1, -2, -3	-L1, -1, -2, -3	-L1, -1, -2, -3	-L1, -1, -2, -3	-L1, -1, -2	-L1, -1, -2	-L1, -1, -2, -3	-L1, -1, -2	-1, -2, -3	-1, -2, -3	-1, -2, -3	-1, -2	
	Extended	—	—	—	—	—	-2	-2	—	-2	—	—	-2	-2	
	Industrial	-L1, -1, -2	-L1, -1, -2	-L1, -1, -2	-L1, -1, -2	-L1, -1, -2	-L1, -1	-L1, -1	-L1, -1, -2	-L1, -1	-1, -2	-1, -2	-1, -2	-1	
Configuration	Configuration Memory (Mb)	26.3	43.8	61.6	73.9	96.1	144.1	184.9	104.5	156.7	79.9	79.9	119.8	160.7	
Package ⁽⁷⁾		Area													
Available User I/O: SelectIO™ Interface Pins ^(4,5) (GTX Low-Power Transceivers, GTH High-Speed Transceivers)															
FFA Packages (FF): Flip-chip, fine-pitch BGA (1.0 mm ball spacing)															
	FF484	23 x 23 mm	240 (8, 0)	240 (8, 0)											
	FF784	29 x 29 mm	360 (12, 0)	400 (12, 0)	400 (12, 0)	400 (12, 0)									
	FF1156	35 x 35 mm		600 (20, 0)	600 (20, 0)	600 (20, 0)	600 (20, 0)		600 (20, 0)	600 (20, 0)					
	FF1759	42.5 x 42.5 mm				720 (24, 0)	720 (24, 0)	840 (36, 0)	720 (24, 0)	840 (36, 0)					
	FF1760	42.5 x 42.5 mm						1,200 (0, 0)	1,200 (0, 0)						
	FF1154	35 x 35 mm									320 (48, 0)		320 (48, 0)		
	FF1155	35 x 35 mm										440 (24, 12)	440 (24, 12)		
	FF1923	45 x 45 mm										480 (24, 24)	720 (40, 24)	720 (40, 24)	
	FF1924	45 x 45 mm											640 (48, 24)	640 (48, 24)	

XMP068 (v1.3)

- Notes:
1. EasyPath FPGAs provide a conversion-free, low-risk path for volume production.
 2. A single Virtex-6 FPGA CLB comprises two slices, each containing four 6-input LUTs and eight flip-flops (twice the number found in a Virtex-4 FPGA slice), for a total of eight 6-input LUTs and 16 flip-flops per CLB.
 3. Virtex-6 FPGA logic cell ratings reflect the increased logic capacity offered by the 6-input LUT architecture.
 4. Digitally Controlled Impedance (DCI) is available on I/Os of all devices.
 5. Supported I/O standards include: HT, LVCMOS (1.2V, 1.5V, 1.8V, 2.5V), HSTL I (1.2V, 1.5V, 1.8V), HSTL II (1.5V, 1.8V), HSTL III (1.5V, 1.8V), LVDS, Extended LVDS, RSDS, Bus LVDS, LVPECL, SSTL I (1.8V, 2.5V), SSTL II (1.8V, 2.5V), and SSTL (1.5V).
 6. One System Monitor block is included in all devices.